

## MM74HC74A

### Dual D-Type Flip-Flop with Preset and Clear

#### General Description

The MM74HC74A utilizes advanced silicon-gate CMOS technology to achieve operating speeds similar to the equivalent LS-TTL part. It possesses the high noise immunity and low power consumption of standard CMOS integrated circuits, along with the ability to drive 10 LS-TTL loads.

This flip-flop has independent data, preset, clear, and clock inputs and Q and  $\bar{Q}$  outputs. The logic level present at the data input is transferred to the output during the positive-going transition of the clock pulse. Preset and clear are independent of the clock and accomplished by a low level at the appropriate input.

The 74HC logic family is functionally and pinout compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

#### Features

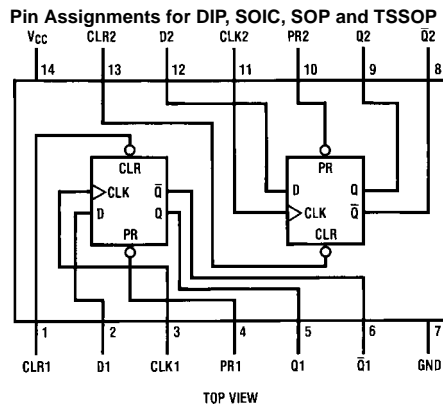
- Typical propagation delay: 20 ns
- Wide power supply range: 2–6V
- Low quiescent current: 40  $\mu$ A maximum (74HC Series)
- Low input current: 1  $\mu$ A maximum
- Fanout of 10 LS-TTL loads

#### Ordering Code:

Order Number	Package Number	Package Description
MM74HC74AM	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC74AMX_NL	M14A	Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC74ASJ	M14D	Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC74AMTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC74AMTCX_NL	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC74AN	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.  
Pb-Free package per JEDEC J-STD-020B.

#### Connection Diagram



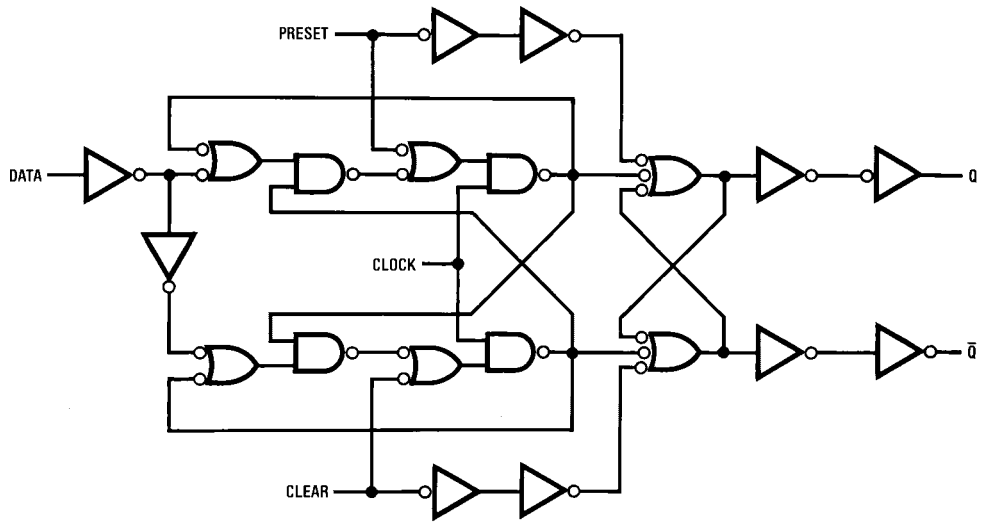
#### Truth Table

Inputs				Outputs	
PR	CLR	CLK	D	Q	$\bar{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H (Note 1)	H (Note 1)
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q0	$\bar{Q}$ 0

**Note:** Q0 = the level of Q before the indicated input conditions were established.

**Note 1:** This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (HIGH) level.

Logic Diagram



**Absolute Maximum Ratings**(Note 2)

(Note 3)

Supply Voltage ( $V_{CC}$ )	-0.5 to +7.0V
DC Input Voltage ( $V_{IN}$ )	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage ( $V_{OUT}$ )	-0.5 to $V_{CC} + 0.5V$
Clamp Diode Current ( $I_{IK}, I_{OK}$ )	$\pm 20$ mA
DC Output Current, per pin ( $I_{OUT}$ )	$\pm 25$ mA
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )	$\pm 50$ mA
Storage Temperature Range ( $T_{STG}$ )	-65°C to +150°C
Power Dissipation ( $P_D$ )	
(Note 4)	600 mW
S.O. Package only	500 mW
Lead Temperature ( $T_L$ )	
(Soldering 10 seconds)	260°C

**Recommended Operating Conditions**

	Min	Max	Units
Supply Voltage ( $V_{CC}$ )	2	6	V
DC Input or Output Voltage ( $V_{IN}, V_{OUT}$ )	0	$V_{CC}$	V
Operating Temperature Range ( $T_A$ )	-40	+85	°C
Input Rise or Fall Times ( $t_r, t_f$ )			
$V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

**Note 2:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.**Note 3:** Unless otherwise specified all voltages are referenced to ground.**Note 4:** Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C.**DC Electrical Characteristics** (Note 5)

Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ C$			$T_A = -40$ to $85^\circ C$	$T_A = -55$ to $125^\circ C$	Units
				Typ	Guaranteed Limits				
$V_{IH}$	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	1.5	V	
			4.5V		3.15	3.15	3.15	V	
			6.0V		4.2	4.2	4.2	V	
$V_{IL}$	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	0.5	V	
			4.5V		1.35	1.35	1.35	V	
			6.0V		1.8	1.8	1.8	V	
$V_{OH}$	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V	2.0	1.9	1.9	1.9	V	
			4.5V	4.5	4.4	4.4	4.4	V	
			6.0V	6.0	5.9	5.9	5.9	V	
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 4.0$ mA $ I_{OUT}  \leq 5.2$ mA	4.5V	4.3	3.98	3.84	3.7	V	
			6.0V	5.2	5.48	5.34	5.2	V	
$V_{OL}$	Maximum LOW Level Output Voltage	$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 20 \mu A$	2.0V	0	0.1	0.1	0.1	V	
			4.5V	0	0.1	0.1	0.1	V	
			6.0V	0	0.1	0.1	0.1	V	
		$V_{IN} = V_{IH}$ or $V_{IL}$ $ I_{OUT}  \leq 4.0$ mA $ I_{OUT}  \leq 5.2$ mA	4.5V	0.2	0.26	0.33	0.4	V	
			6.0V	0.2	0.26	0.33	0.4	V	
$I_{IN}$	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		$\pm 0.1$	$\pm 1.0$	$\pm 1.0$	$\mu A$	
$I_{CC}$	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		4.0	40	80	$\mu A$	

**Note 5:** For a power supply of 5V  $\pm 10\%$  the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5V$  and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

## AC Electrical Characteristics

$V_{CC} = 5V$ ,  $T_A = 25^\circ C$ ,  $C_L = 15\text{ pF}$ ,  $t_r = t_f = 6\text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
$f_{MAX}$	Maximum Operating Frequency		72	30	MHz
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay Clock to Q or $\bar{Q}$		10	30	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay Preset or Clear to Q or $\bar{Q}$		17	40	ns
$t_{REM}$	Minimum Removal Time, Preset or Clear to Clock		6	5	ns
$t_s$	Minimum Setup Time Data to Clock		10	20	ns
$t_H$	Minimum Hold Time Clock to Data		0	0	ns
$t_W$	Minimum Pulse Width Clock, Preset or Clear		8	16	ns

## AC Electrical Characteristics

$C_L = 50\text{ pF}$ ,  $t_r = t_f = 6\text{ ns}$  (unless otherwise specified)

Symbol	Parameter	Conditions	$V_{CC}$	$T_A = 25^\circ C$		$T_A = -40\text{ to }85^\circ C$	$T_A = -55\text{ to }125^\circ C$	Units
				Typ	Guaranteed Limits			
$f_{MAX}$	Maximum Operating Frequency		2.0V	22	6	5	4	MHz
			4.5V	72	30	24	20	MHz
			6.0V	94	35	28	24	MHz
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay Clock to Q or $\bar{Q}$		2.0V	34	110	140	165	ns
			4.5V	12	22	28	33	ns
			6.0V	10	19	24	28	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay Preset or Clear To Q or $\bar{Q}$		2.0V	66	150	190	225	ns
			4.5V	20	30	38	45	ns
			6.0V	16	26	33	38	ns
$t_{REM}$	Minimum Removal Time Preset or Clear To Clock		2.0V	20	50	65	75	ns
			4.5V	6	10	13	15	ns
			6.0V	5	9	11	13	ns
$t_s$	Minimum Setup Time Data to Clock		2.0V	35	80	100	120	ns
			4.5V	10	16	20	24	ns
			6.0V	8	14	17	20	ns
$t_H$	Minimum Hold Time Clock to Data		2.0V		0	0	0	ns
			4.5V		0	0	0	ns
			6.0V		0	0	0	ns
$t_W$	Minimum, Pulse Width Clock, Preset or Clear		2.0V	30	80	101	119	ns
			4.5V	9	16	20	24	ns
			6.0V	8	14	17	20	ns
$t_{TLH}$ , $t_{THL}$	Maximum Output Rise and Fall Time		2.0V	25	75	95	110	ns
			4.5V	7	15	19	22	ns
			6.0V	6	13	16	19	ns
$t_r$ , $t_f$	Maximum Input Rise and Fall Time		2.0V		1000	1000	1000	ns
			4.5V		500	500	500	ns
			6.0V		400	400	400	ns
$C_{PD}$	Power Dissipation Capacitance (Note 6)	(per flip-flop)		80				pF
$C_{IN}$	Maximum Input Capacitance			5	10	10	10	pF

**Note 6:**  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} V_{CC} f + I_{CC}$ .

**Physical Dimensions** inches (millimeters) unless otherwise noted



**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

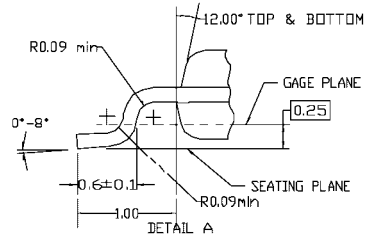
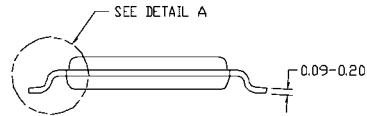
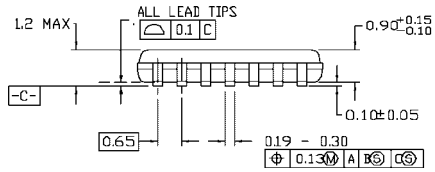
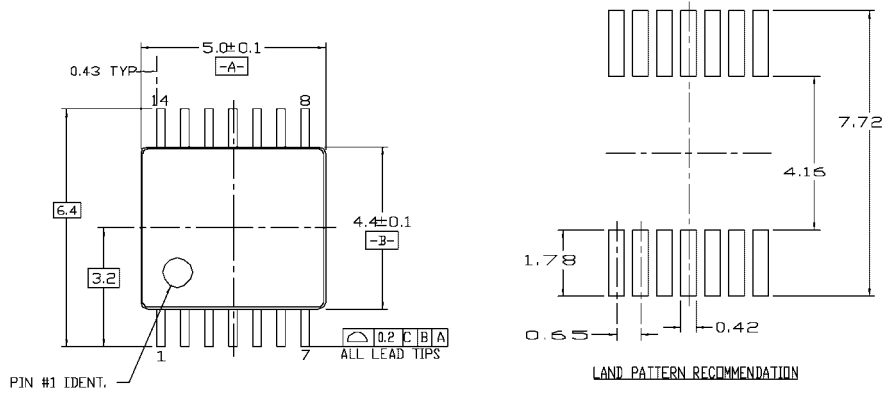
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 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1



**Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M14D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153 VARIATION AB, REF NOTE 6, DATED 7/93
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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